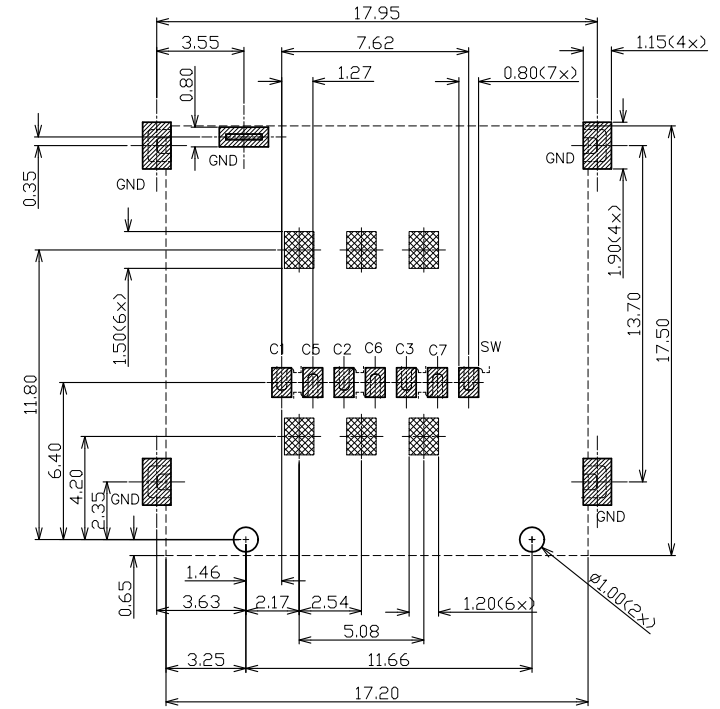
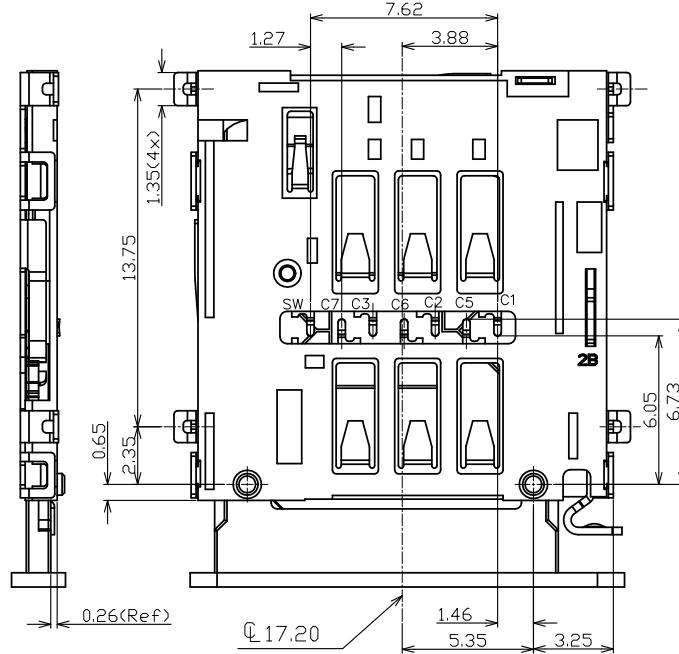
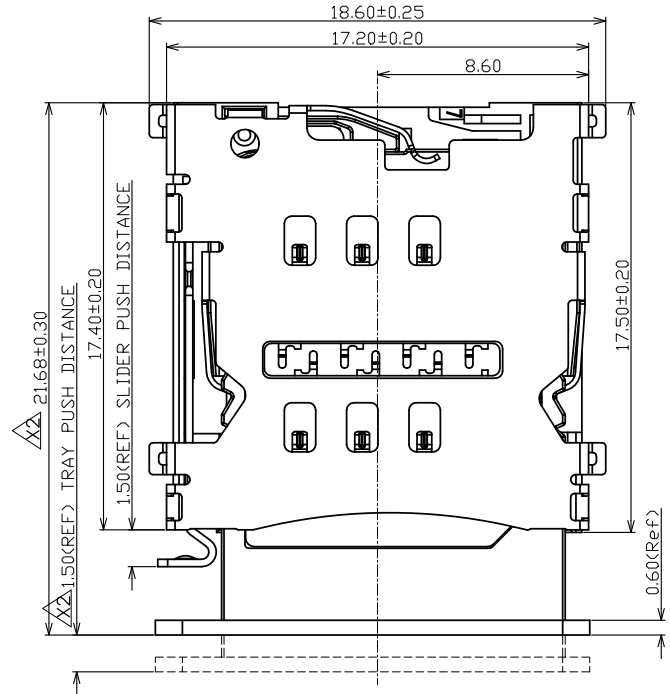


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Apr.14.2018
X2	Change DIM				Oct.14.2021

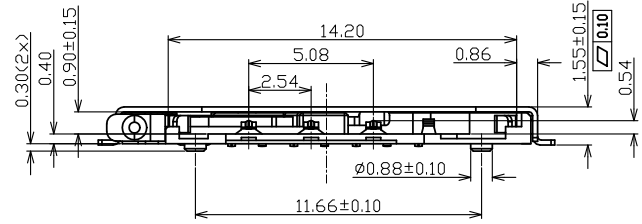


RECOMMENDED P.C.B LAYOUT COMPONENT SIDE (TOLERANCE ±0.05)

▨ PAD AREA

--- CONNECTOR OUTLINE

▣ NO PATTERN AND VIA HOLE IN THIS AREA



**TECHNICAL CHARACTERISTICS**

1.General Characteristics  
 Dimensions:17.20LX17.50WX1.55H mm  
 TRAY MATING FORCE:2~10N  
 TRAY UNMATING FORCE:4~10N  
 Durability:3,000 cycles min.

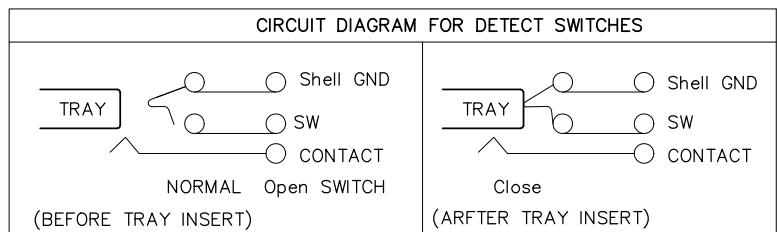
2.Electrical Characteristics  
 Contact resistance:50mΩ typical, 100mΩMax  
 Insulation resistance:>1000M/500V DC

3.Solderability  
 Vaporphase:215°C, 30sec.Max  
 IR reflow:260°C,5sec.Max  
 Manual soldering:370°C.3sec.Max

4.Environmental Characteristics  
 Operating temperature:-40°C~+85°C  
 Operating humidity:10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated
5	Lever		Stainless Steel	
6	Cam		Stainless Steel	

NANO SIM CARD	
Pin No.	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



Unless otherwise specified, other tolerance are:

**MUP MUP INDUSTRIAL CO.,LTD.**

NAME: **SINGLE Micro SIM Card Connector**

MODEL NO: **MUP-C7902-1A**

TYPE: **H1.55mm Normally Open & With Tray type**

PROJ.	UNIT	SCALE	DRAWN	Henry Ou.04.2018	DWG NO.:
±0.35	mm	1:1	CHECKED	Henry Ou.04.2018	DWG-MUP-C7902-1A
±0.25			APPROVAL	Simon 04.2018	SHEET
±0.15					1/1
±0.10					REVISION
					X2

